

## WAFER PREPARATION & DIE SORT



### Capabilities:

- Wafer Dicing up to 300mm
- Backgrinding
- Silicon, Quartz, Glass, Ceramic, Laminates, etc.
- Multi-Project Wafers (MPW)
- Die Sort into Various Media (Gel-Pak, Waffle Pack)
- Same-Day Service Available
- Prototype to Medium Volume
- Cleanroom Environment
- Outstanding Quality and Customer Service

Whether you are a fabless Semiconductor company needing a complete turn-key packaging and assembly solution for your new designs or an Integrated Device Manufacturer (IDM) with internal prototype assembly capability, Quik-Pak can provide wafer and die preparation services to meet your requirements.

### Wafer Dicing

Disco automatic equipment will precisely dice your wafers or substrates including multi-project or "pizza" wafers. Kerf widths as narrow as 15 $\mu$ m. Automatic kerf width/chip-out monitoring.

### Silicon Wafer Coring

Silicon wafer coring from wafers as large as 12" (305mm) for custom extraction of smaller development wafers.

### Backgrinding

Wafers can be thinned down to 52 $\mu$ m to accommodate the latest package technology and stacked die applications.

### Pick & Place

Have your die sorted into Gel-Pak's® or waffle packs.

### Quick-Turn Service

When you need to meet a project or customer deadline, you can count on Quik-Pak's reliable on-time delivery options including same-day expedited service. In fact, we can receive a wafer in the morning and ship completely assembled devices by the end of the day.

When you require a full turnkey provider of production-quality prototype parts for internal testing or customer samples, Quik-Pak is the answer. Services include Wafer Backgrinding & Dicing, Package Procurement & Open Cavity Preparation, Die Attach, Wire boning, Encapsulation, Remolding and Marking.

### Quik-Pak

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